

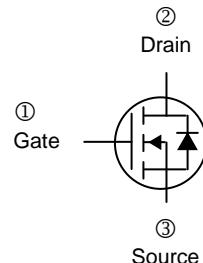
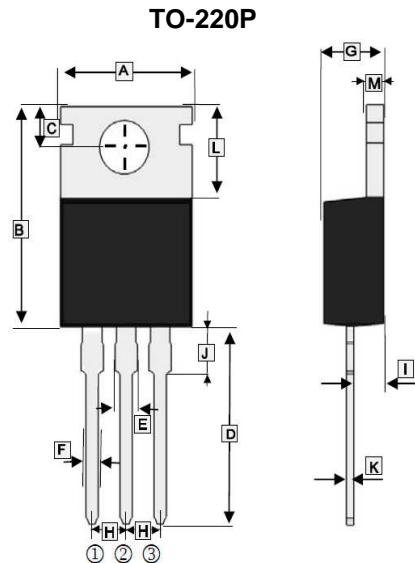
RoHS Compliant Product  
A suffix of "-C" specifies halogen free

## DESCRIPTION

The SSE04N60SL is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent R<sub>DS(on)</sub> and gate charge for most of the synchronous buck converter applications.

## FEATURES

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	9.3	10.6	H	2.54	BCS.
B	14.2	16.5	I	1.8	2.9
C	2.7	BSC.	J	2.6	3.95
D	12.6	14.7	K	0.3	0.6
E	1.0	1.8	L	5.8	7.0
F	0.4	1.0	M	1.2	1.45
G	3.6	4.8			

## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	600	V
Gate-Source Voltage	V <sub>GS</sub>	±30	V
Continuous Drain Current T <sub>C</sub> =25°C	I <sub>D</sub>	4	A
T <sub>C</sub> =100°C		2.5	A
Pulsed Drain Current	I <sub>DM</sub>	16	A
Total Power Dissipation T <sub>C</sub> =25°C	P <sub>D</sub>	100	W
Derate above 25°C		0.8	
Single Pulse Avalanche Energy <sup>1</sup>	E <sub>AS</sub>	217	mJ
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55~150	°C
Thermal Resistance Rating			
Maximum Thermal Resistance Junction-Ambient	R <sub>θJA</sub>	62.5	°C / W
Maximum Thermal Resistance Junction-Case	R <sub>θJC</sub>	1.25	°C / W

Notes:

1. L=30mH, I<sub>AS</sub>=3.45A, V<sub>DD</sub>=155V, R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C

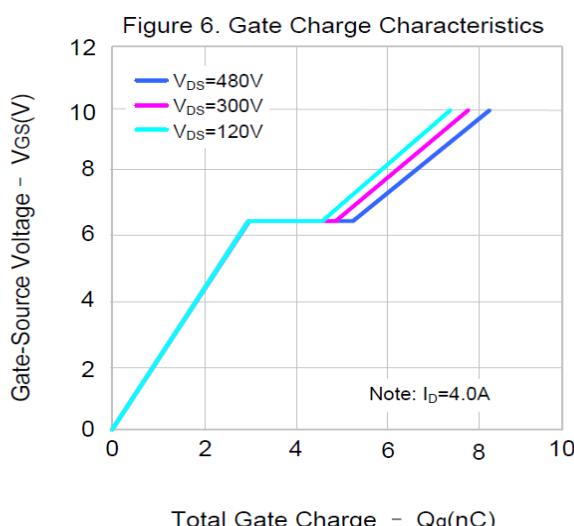
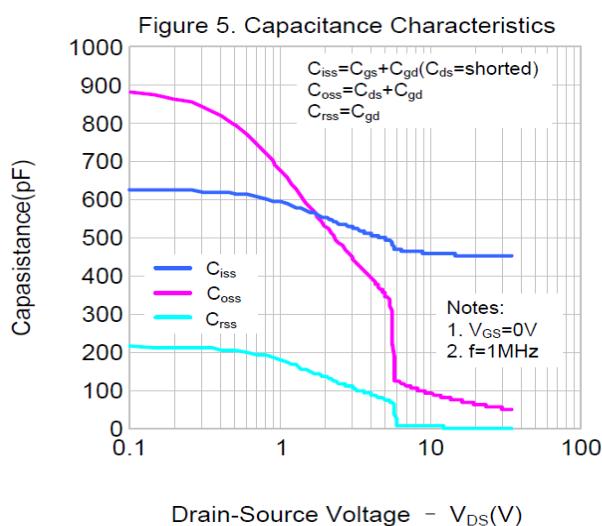
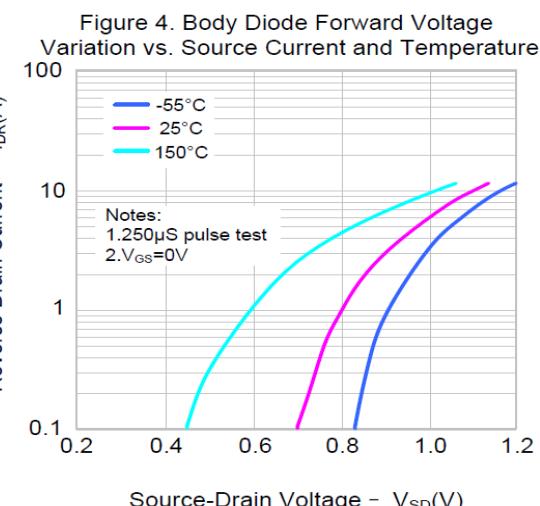
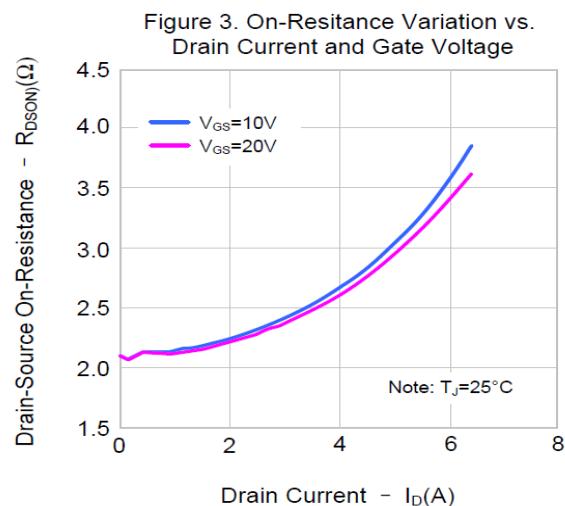
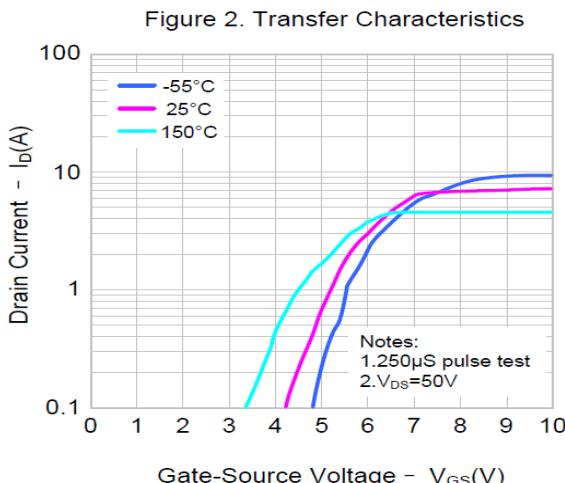
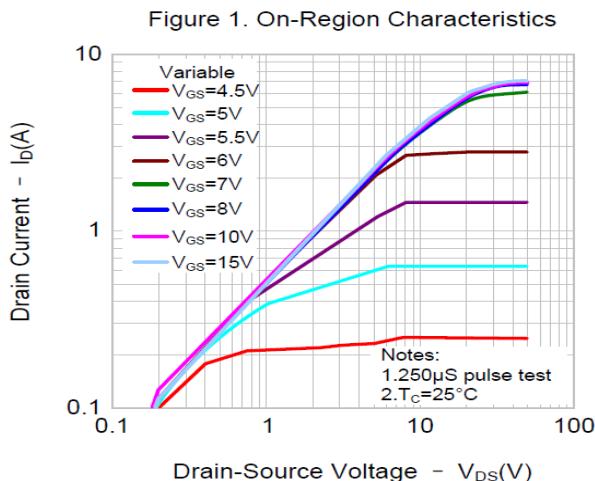
**ELECTRICAL CHARACTERISTICS** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	600	-	-	V	$V_{GS}=0$ , $I_D=250\mu\text{A}$
Gate-Threshold Voltage	$V_{GS(\text{th})}$	2	-	4	V	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$
Gate-Source Leakage Current	$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS} = \pm 30\text{V}$
Drain-Source Leakage Current	$I_{DSS}$	-	-	1	$\mu\text{A}$	$V_{DS}=600\text{V}$ , $V_{GS}=0$
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	-	2.0	2.4	$\Omega$	$V_{GS}=10\text{V}$ , $I_D=2\text{A}$
Total Gate Charge <sup>1,2</sup>	$Q_g$	-	8.16	-	nC	$I_D=4\text{A}$ $V_{DS}=480\text{V}$ $V_{GS}=10\text{V}$
Gate-Source Charge <sup>1,2</sup>	$Q_{gs}$	-	2.63	-		
Gate-Drain Charge <sup>1,2</sup>	$Q_{gd}$	-	3.01	-		
Turn-on Delay Time <sup>1,2</sup>	$T_{d(\text{on})}$	-	16.8	-	ns	$V_{DD}=300\text{V}$ $I_D=4\text{A}$ $R_G=25\Omega$
Rise Time <sup>1,2</sup>	$T_r$	-	26.2	-		
Turn-off Delay Time <sup>1,2</sup>	$T_{d(\text{off})}$	-	37.4	-		
Fall Time <sup>1,2</sup>	$T_f$	-	20.2	-		
Input Capacitance	$C_{iss}$	-	449.7	-	pF	$V_{GS}=0$ $V_{DS}=25\text{V}$ $f=1.0\text{MHz}$
Output Capacitance	$C_{oss}$	-	57	-		
Reverse Transfer Capacitance	$C_{rss}$	-	2	-		
<b>Source-Drain Diode</b>						
Diode Forward Voltage	$V_{SD}$	-	-	1.4	V	$I_S=4\text{A}$ , $V_{GS}=0$
Continuous Source Current	$I_S$	-	-	4	A	Integral Reverse P-N Junction Diode in the MOSFET
Pulsed Source Current	$I_{SM}$	-	-	16	A	
Reverse Recovery Time <sup>1</sup>	$T_{rr}$	-	441.53	-	ns	$I_S=4\text{A}$ , $V_{GS}=0$ , $dI_F/dt=100\text{A}/\mu\text{s}$
Reverse Recovery Charge <sup>1</sup>	$Q_{rr}$	-	1.98	-	$\mu\text{C}$	

Notes:

1. Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$
2. Essentially independent of operating temperature.

## CHARACTERISTIC CURVES



## CHARACTERISTIC CURVES

Figure 7. Breakdown Voltage Variation vs. Temperature

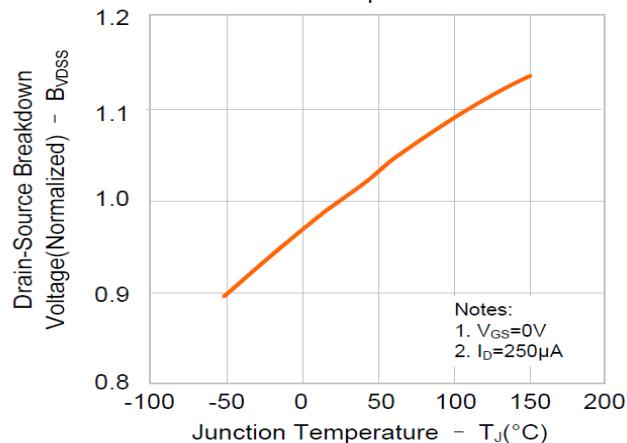


Figure 8. On-resistance Variation vs. Temperature

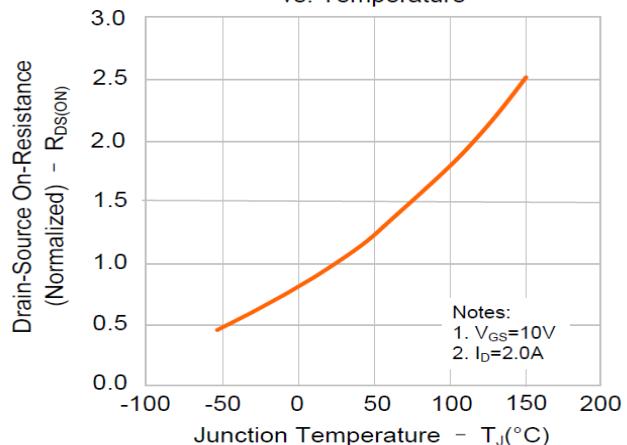


Figure 9 Max. Safe Operating Area

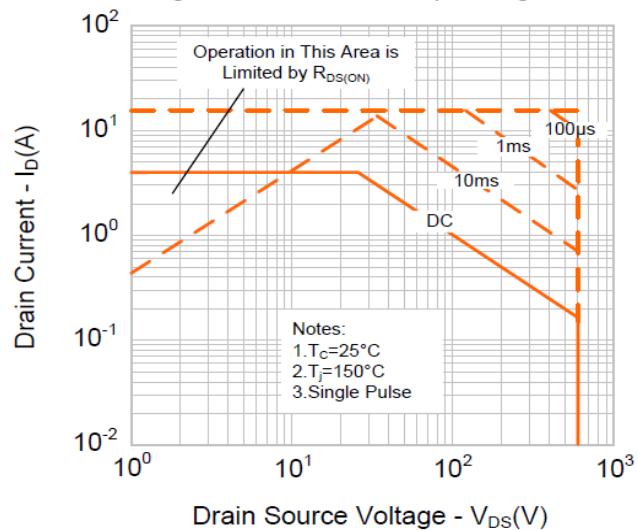
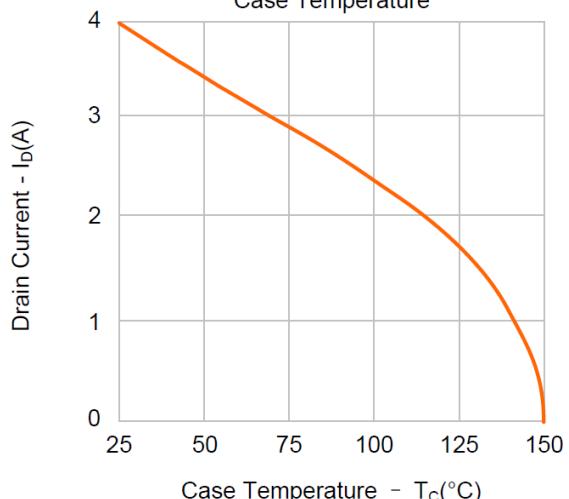
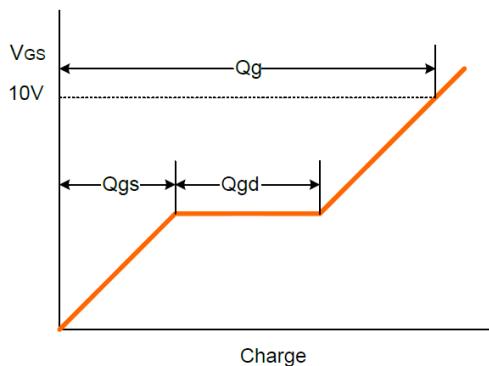
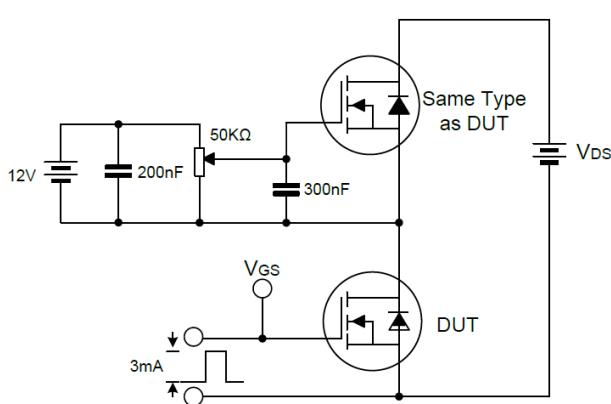


Figure 10. Maximum Drain Current vs. Case Temperature

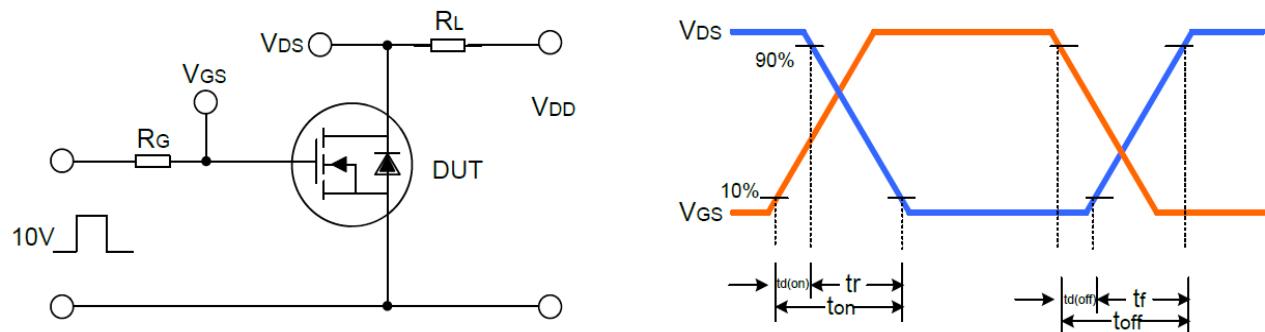


Gate Charge Test Circuit & Waveform



## CHARACTERISTIC CURVES

Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveform

